

## 32-bit Single Chip Microcomputer

- 32-bit S1C33000 RISC Core
- Low Power
- Multiply Accumulation
- Built-in 16K-byte RAM
- 10-bit ADC
- Built-in LCD Controller
- Built-in USB1.1 Function Controller
- Built-in SDRAM Controller

### ■ DESCRIPTION

The S1C33L05 is a Seiko Epson original 32-bit microcomputer that features high speed, low power consumption, and low-voltage operation. The S1C33L05 consists of an S1C33000 32-bit RISC type CPU as its core, peripheral circuits including a bus control unit, DMA controller, interrupt controller, timers, serial interface with FIFO, A/D converter, a color STN LCD controller that supports 64K color display, SDRAM controller, USB1.1 function controller, sequential ROM interface, MMC (SPI mode) interface and NAND flash interface, and also an embedded RAM. Two oscillation circuits and a PLL are also included, supporting advanced operation, power-saving operation, and high-performance realtime clock functions. The S1C33L05 is ideal for portable products that require high-speed data processing. Especially it is suitable for the application processor embedded in PDAs, electronic dictionary and e-Book readers.

### ■ FEATURES

#### ● Core CPU

Seiko Epson original 32-bit RISC CPU S1C33000 built-in

- Basic instruction set: 105 instructions (16-bit fixed size)
- Sixteen 32-bit general-purpose register
- 32-bit ALU and 8-bit shifter
- Multiplication/division instructions and MAC (multiplication and accumulation) instruction are available
- 20.83 ns of minimum instruction execution time at 48 MHz operation

#### ● Internal memory

General-purpose RAM ..... 16K bytes (1-cycle-access)

Video-RAM ..... 40K bytes (usable for general-purpose RAM, 2-cycle-access)

#### ● Internal peripheral circuits

OSC3 oscillation circuit/PLL ..... When PLL is disabled

Crystal oscillator 5 MHz min. to 48 MHz max.

Ceramic oscillator 48 MHz (fixed)

External clock input 2 MHz min. to 48 MHz max.

When PLL is enabled

Crystal oscillator 20 MHz min. to 48 MHz max.

Ceramic oscillator 48 MHz (fixed)

External clock input 20 MHz min. to 48 MHz max.

Generates the main clock for the bus and the CPU.

The software controllable PLL multiplies the high-speed (OSC3) oscillation clock frequency.

PLL input clock 10 MHz min. to 24 MHz max.

PLL output clock 10 MHz min. to 48 MHz max.

OSC1 oscillation circuit ..... Crystal oscillator or external clock input 32.768 kHz typ.

Generates the source clock for the realtime clock function, etc.

# S1C33L05

Timers .....	8-bit timer	6 channels
	16-bit timer	6 channels
	Watchdog timer	1 channel (16-bit timer 0's function)
	Clock timer	1 channel (with alarm function)
Serial interface .....	4 channels	
	Clock-synchronous system, asynchronous system and IrDA 1.0 interface are selectable.	
	Ch.0 is selectable between a built-in buffer type (a 4-byte receive-data buffer and a 2-byte transmit-data buffer) and no buffer type.	
A/D converter .....	10 bits × 5 channels	
LCD controller .....	4 or 8-bit monochrome/color LCD interface	
	Panels supported	
	- Single-panel, single drive passive display	
	- 4/8-bit monochrome LCD interface	
	- 4/8-bit color LCD interface	
	Display modes	
	- 16-bpp mode: 64K colors or 64-level gray scale display	
	- 12-bpp mode: 4096 colors or 16-level gray scale display	
	- 8-bpp mode: 256 colors or 64-level gray scale display	
	- 4-bpp mode: 16 colors or 16-level gray scale display	
	- 2-bpp mode: 4 colors or 4-level gray scale display	
	- 1-bpp mode: 2 colors or 2-level gray scale display	
	* A 256 × 3 × 6-bit Look-Up Table (256K-color palette) is provided for displaying 256 colors simultaneously. The LUT can be bypassed to send display data from VRAM directly to the LCD.	
	* Gray scale display uses FRM (Frame Rate Modulation) and dithering.	
	Resolution (programmable)	
	Typical resolutions when only the internal VRAM is used:	
	- 320 × 240 pixels in 4-bpp mode	
	- 160 × 240 pixels in 8-bpp mode	
	- 160 × 160 pixels in 12-bpp mode	
	Typical resolutions when an external VRAM is used via the UMA:	
	- 320 × 240 pixels in 8-bpp mode	
	- 320 × 240 pixels in 16-bpp mode	
SDRAM controller .....	48 MHz synchronous clock max.	
	Supports up to 256M-bit (32MB) SDRAM with 16-bit data width. 16-stage IQB (32-byte Instruction Queue Buffer) and 2-stage DQB (4-byte Data Queue Buffer) are provided.	
	Allows LCDC DMA controller to access SDRAM directly as an external VRAM.	
MMC (SPI mode) interface .....	1 channel	
	Supports 1 to 16-bit serial data transfer in master mode.	
	Compatible with MMC.	

NAND flash interface .....	Generates the #SMWE and #SMRE signals using the BCU signals to interface directly with SmartMedia cards or NAND flash memories. Supports 8/16-bit Nand flash devices. Also the Nand flash booting function and the ECC function when a Nand flash is read/written are supported.
Sequential ROM interface .....	Supports MX23L12813 (manufactured by Macronix International Co., Ltd.). Generates the SQUALE, SQLALE and #SQRD signals using the BCU signals to interface directly with the sequential mask ROM.
USB1.1 function controller .....	Endpoint: EP0, EPa, EPb, EPc, EPd (4 channels); FIFO: 1,024 bytes
DMA controller .....	High-speed DMA      4 channels High-speed DMA Ch. 3 has been reserved for the internal USB1.1 function controller. Intelligent DMA      128 channels
Interrupt controller .....	Possible to invoke DMA Input interrupt                      10 types (programmable) DMA controller interrupt            5 types 16-bit programmable timer interrupt 12 types 8-bit programmable timer interrupt 6 types Serial interface interrupt            15 types A/D converter interrupt              1 type Clock timer interrupt                1 type LCD controller interrupt             1 type SPI interrupt                          1 type USB function controller interrupt   1 type
General-purpose input and output ports ...	Shared with the I/O pins for internal peripheral circuits Input port      9 bits (max.) I/O port      69 bits (max.)  * The K54 and K65–K67 pins are not available in the S1C33L05. * Two LED direct output (8 mA) ports (P27 and P26) are available. * The number of the ports varies depending on the peripheral functions used.

● External bus interface

BCU (bus control unit) built-in

- 26-bit address bus (internal 28-bit processing)
- 16-bit data bus (Data size is selectable from 8 bits and 16 bits in each area.)
- Little/big-endian memory access; endian type may be set in each area.
- Memory mapped I/O
- Chip enable and wait control circuits built-in
- Supports burst ROM.

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## ● Operating conditions and power consumption

Operating voltage .....	Core (VDD)	1.65 V to 1.95 V (1.8 V $\pm$ 0.15 V) (when crystal oscillator is used)
		1.70 V to 1.90 V (1.8 V $\pm$ 0.10 V) (when ceramic oscillator is used)
	I/O (VDDE, AVDDE)	2.70 V to 3.60 V (when USB is not used)
		3.00 V to 3.60 V (when USB is used)
Operating clock frequency .....	CPU	48 MHz max. <sup>Note 1</sup>
	Bus (BCU)	40 MHz max.
	LCD controller	48 MHz max.
	USB function controller	48 MHz
	SDRAM	48 MHz
Operating temperature .....		-40 to 85°C (when crystal oscillator is used)
		0 to 70°C (when ceramic oscillator is used)
Power consumption .....	During SLEEP	12 $\mu$ W typ.
	During HALT	18 mW typ. (48 MHz, LCDC and USB not included)
	During execution	42 mW typ. <sup>Note 2</sup> (48 MHz, LCDC and USB not included)
	LCD controller	
	- During display	1.8 mW typ. (LCDC clock = 8 MHz, 16 bpp, IVRAM mode, VDD, LCDC block only)
	USB controller	
	- Idle state	14 mW typ. (VDD, USB block only)

## ● Supply form

Plastic package .....	QFP21-176pin (24 mm $\times$ 24 mm $\times$ 1.4 mm, 0.5-mm pitch)
Die form .....	167-PAD (5.25 mm $\times$ 4.85 mm, 100 $\mu$ m pitch)

Notes: 1. Set the #X2SPD pin to "0" when running the CPU with a 40 MHz or more system clock. Also make sure that the internal bus operating clock frequency does not exceed 40 MHz.

2. The values of power consumption during execution were measured when a test program that consisted of 55% load instructions, 23% arithmetic operation instructions, 1% mac instruction, 12% branch instructions and 9% ext instruction was being continuously executed.

## ■ BLOCK DIAGRAM

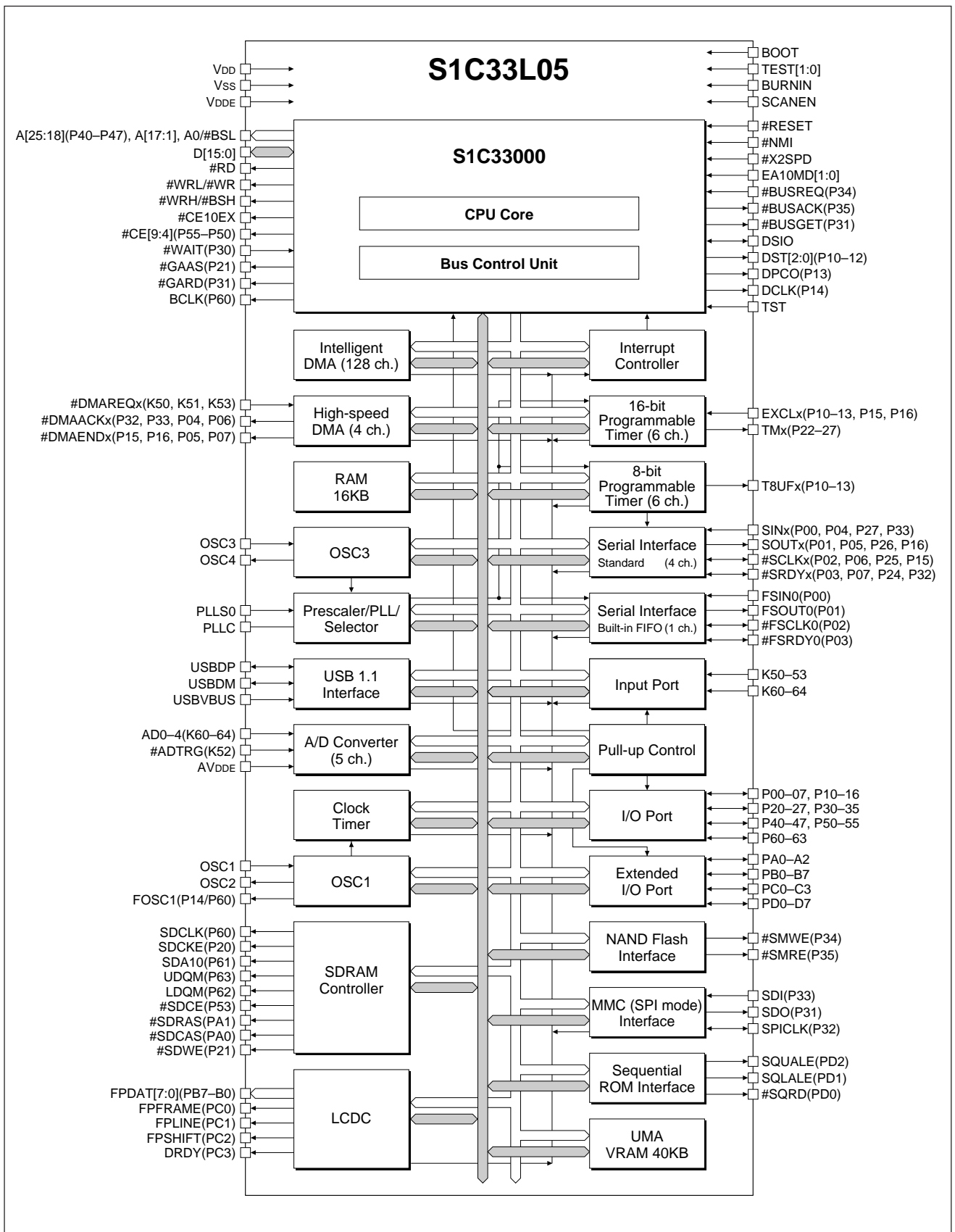
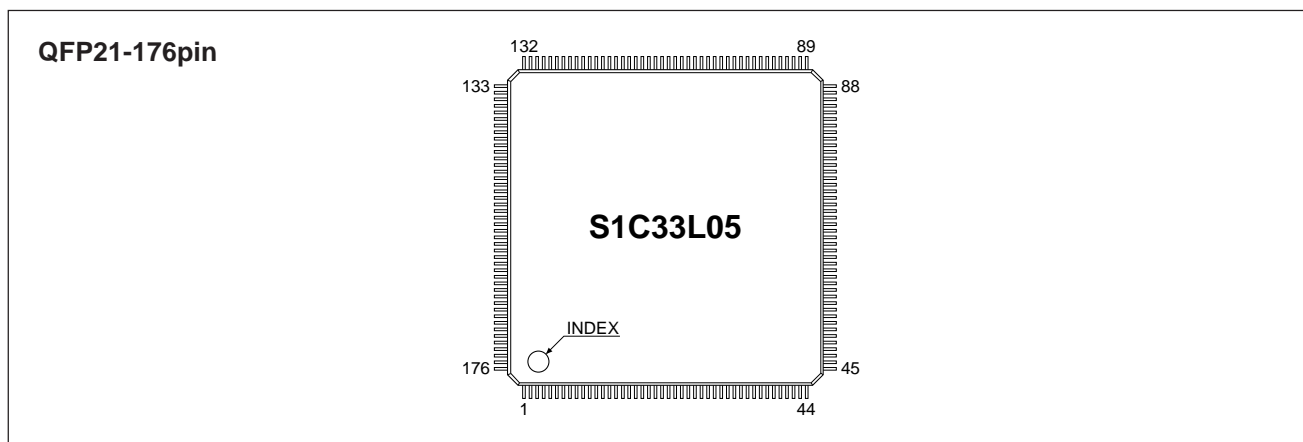


Fig. 1 S1C33L05 Functional Block Diagram

# S1C33L05

## PIN LAYOUT



No.	Pin name	No.	Pin name	No.	Pin name	No.	Pin name
1	<b>D9</b>	45	<b>P15/EXCL4/#DMAEND0/#SCLK3</b>	89	<b>P01/SOUT0/FSOUT0</b>	133	<b>A23/P42</b>
2	<b>D8</b>	46	N.C.	90	<b>P00/SIN0/FSIN0</b>	134	N.C.
3	<b>VdDE</b>	47	<b>DSIO</b>	91	<b>USBDP</b>	135	<b>A22/P43</b>
4	<b>D7</b>	48	<b>VdDE</b>	92	<b>USBDM</b>	136	<b>A21/P44</b>
5	<b>D6</b>	49	<b>DCLK/P14/FOSC1</b>	93	N.C.	137	<b>A20/P45</b>
6	<b>D5</b>	50	<b>DPCO/P13/EXCL3/T8UF3</b>	94	<b>USBVBUS</b>	138	<b>A19/P46</b>
7	<b>D4</b>	51	<b>DST2/P12/EXCL2/T8UF2</b>	95	<b>VdDE</b>	139	<b>A18/P47</b>
8	<b>D3</b>	52	<b>DST1/P11/EXCL1/T8UF1</b>	96	<b>P31/#BUSGET/#GARD/SDO</b>	140	<b>A17</b>
9	<b>D2</b>	53	<b>DST0/P10/EXCL0/T8UF0</b>	97	<b>P32/#DMAACK0/#SRDY3/SPICLK</b>	141	<b>A16</b>
10	<b>D1</b>	54	<b>VdD</b>	98	<b>Vss</b>	142	<b>VdDE</b>
11	<b>D0</b>	55	<b>#NMI</b>	99	<b>P33/#DMAACK1/SIN3/SDI</b>	143	<b>A15</b>
12	<b>Vss</b>	56	<b>#RESET</b>	100	<b>P34/#BUSREQ/#CE6/#SMWE</b>	144	<b>A14</b>
13	<b>P30/#WAIT/#CE4&amp;5/PA2</b>	57	N.C.	101	<b>P35/#BUSACK/#SMRE</b>	145	N.C.
14	<b>PD0/#SQRD</b>	58	<b>Vss</b>	102	<b>VdD</b>	146	<b>A13</b>
15	<b>PD1/SQALE</b>	59	<b>K60/AD0</b>	103	<b>#X2SPD</b>	147	<b>A12</b>
16	<b>PD2/SQALE</b>	60	<b>K61/AD1</b>	104	<b>EA10MD0</b>	148	<b>Vss</b>
17	<b>PD3</b>	61	<b>K62/AD2</b>	105	<b>EA10MD1</b>	149	<b>A11</b>
18	<b>PD4</b>	62	<b>K63/AD3</b>	106	<b>VdDE</b>	150	<b>A10</b>
19	<b>PD5</b>	63	<b>K64/AD4</b>	107	<b>PLL</b>	151	<b>VdD</b>
20	<b>PD6</b>	64	<b>TEST0</b>	108	<b>Vss</b>	152	<b>A9</b>
21	<b>PD7</b>	65	<b>AVdDE</b>	109	<b>PLLS0</b>	153	<b>A8</b>
22	<b>VdDE</b>	66	<b>K53/#DMAREQ2</b>	110	<b>TST</b>	154	<b>A7</b>
23	<b>P22/TM0</b>	67	<b>K52/#ADTRG</b>	111	<b>BOOT</b>	155	<b>A6</b>
24	<b>P23/TM1</b>	68	<b>K51/#DMAREQ1</b>	112	<b>#CE4/#CE11/#CE11&amp;12/P50</b>	156	<b>A5</b>
25	<b>P24/TM2/#SRDY2</b>	69	<b>K50/#DMAREQ0</b>	113	<b>Vss</b>	157	<b>Vss</b>
26	<b>P25/TM3/#SCLK2</b>	70	<b>Vss</b>	114	<b>#CE5/#CE15/#CE15&amp;16/P51</b>	158	<b>A4</b>
27	<b>P26/TM4/SOUT2</b>	71	<b>OSC1</b>	115	<b>#CE6/#CE7&amp;8/P52</b>	159	<b>A3</b>
28	<b>P27/TM5/SIN2</b>	72	<b>OSC2</b>	116	<b>#CE7/#RAS0/#CE13/#RAS2/P53/#SDCE</b>	160	<b>VdDE</b>
29	<b>Vss</b>	73	<b>VdDE</b>	117	<b>#CE8/#RAS1/#CE14/#RAS3/P54</b>	161	<b>A2</b>
30	<b>PB7/FPDAT7</b>	74	<b>BURNIN</b>	118	<b>#CE9/#CE17/#CE17&amp;18/P55</b>	162	<b>A1</b>
31	<b>PB6/FPDAT6</b>	75	<b>SCANEN</b>	119	<b>#CE10EX/#CE9&amp;10EX</b>	163	<b>A0/#BSL</b>
32	<b>PB5/FPDAT5</b>	76	<b>TEST1</b>	120	<b>P61/SDA10</b>	164	<b>#WRH/#BSH</b>
33	<b>PB4/FPDAT4</b>	77	N.C.	121	<b>P62/LDQM</b>	165	N.C.
34	<b>VdD</b>	78	<b>VdD</b>	122	<b>P63/UDQM</b>	166	<b>#WRL/#WR/#WE</b>
35	<b>PB3/FPDAT3</b>	79	<b>OSC3</b>	123	<b>P21/#DWE/#GAAS/#SDWE</b>	167	<b>#RD</b>
36	<b>PB2/FPDAT2</b>	80	<b>OSC4</b>	124	<b>#LCAS/PA0/#SDCAS</b>	168	<b>Vss</b>
37	<b>PB1/FPDAT1</b>	81	<b>Vss</b>	125	<b>VdD</b>	169	<b>D15</b>
38	<b>PB0/FPDAT0</b>	82	<b>P07/#SRDY1/#DMAEND3</b>	126	<b>#HCAS/PA1/#SDRAS</b>	170	<b>D14</b>
39	<b>PC3/DRDY</b>	83	<b>P06/#SCLK1/#DMAACK3</b>	127	<b>P20/#DRD/SDCKE</b>	171	<b>D13</b>
40	<b>PC2/FPSHIFT</b>	84	<b>P05/#SOUT1/#DMAEND2</b>	128	<b>VdDE</b>	172	<b>D12</b>
41	<b>PC1/FPPLINE</b>	85	<b>P04/#SIN1/#DMAACK2</b>	129	<b>BCLK/P60/FOSC1/SDCLK</b>	173	<b>D11</b>
42	<b>PC0/FPFRAME</b>	86	<b>P03/#SRDY0/#FSRDY0</b>	130	<b>A25/P40</b>	174	<b>VdD</b>
43	<b>Vss</b>	87	<b>P02/#SCLK0/#FSCLK0</b>	131	<b>Vss</b>	175	<b>D10</b>
44	<b>P16/EXCL5/#DMAEND1/SOUT3</b>	88	N.C.	132	<b>A24/P41</b>	176	N.C.

**Bold:** The pin (signal) name of a default setup.

Fig. 2 Pin Layout Diagram (QFP21-176pin)

## BASIC EXTERNAL CONNECTION DIAGRAM

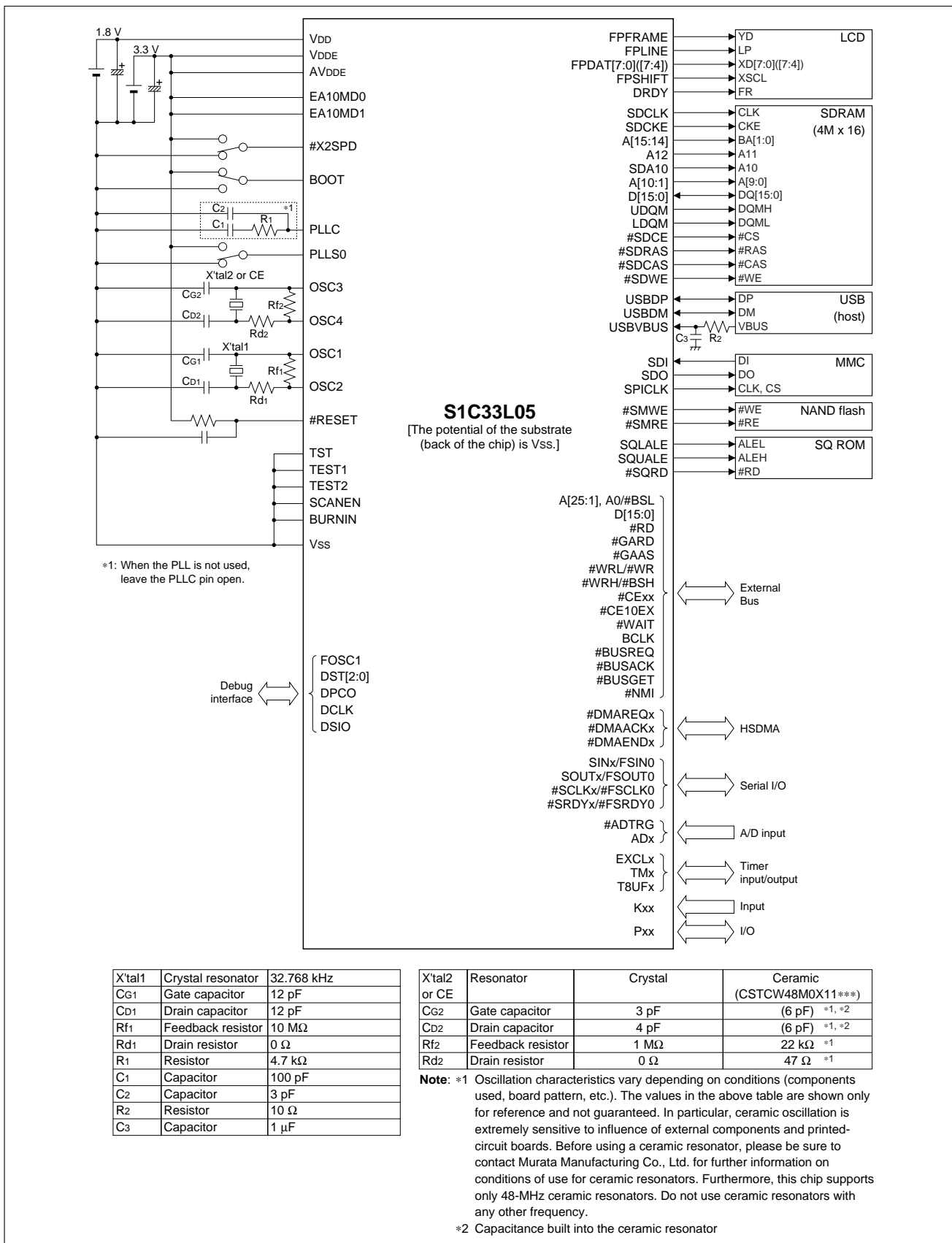


Fig. 3 Basic External Connection Diagram

# S1C33L05

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